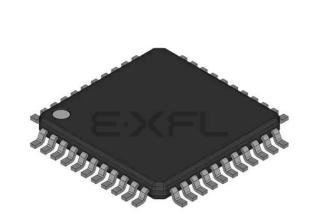
E·XFL

Altera - EPM7032BTC44-7 Datasheet



Welcome to E-XFL.COM

Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	2
Number of Macrocells	32
Number of Gates	600
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=epm7032btc44-7

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPMs), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, and VeriBest
- Programming support with Altera's Master Programming Unit (MPU), MasterBlasterTM serial/universal serial bus (USB) communications cable, and ByteBlasterMVTM parallel port download cable, as well as programming hardware from thirdparty manufacturers and any JamTM STAPL File (.jam), Jam Byte-Code File (.jbc), or Serial Vector Format File (.svf)-capable incircuit tester

MAX 7000B devices are high-density, high-performance devices based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000B devices operate with a 2.5-V supply voltage and provide 600 to 10,000 usable gates, ISP, pin-to-pin delays as fast as 3.5 ns, and counter speeds up to 303.0 MHz. See Table 2.

Table 2. MAX 7000B Speed Grades Note (1)					
Device		Speed Grade			
	-3	-4	-5	-7	-10
EPM7032B	\checkmark		\checkmark	\checkmark	
EPM7064B	~		\checkmark	\checkmark	
EPM7128B		\checkmark		\checkmark	\checkmark
EPM7256B			\checkmark	\checkmark	\checkmark
EPM7512B			\checkmark	\checkmark	\checkmark

Notes:

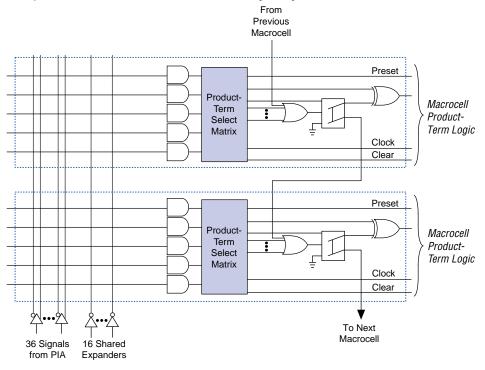
 Contact Altera Marketing for up-to-date information on available device speed grades.

The MAX 7000B architecture supports 100% TTL emulation and highdensity integration of SSI, MSI, and LSI logic functions. It easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000B devices are available in a wide range of packages, including PLCC, BGA, FineLine BGA, 0.8-mm Ultra FineLine BGA, PQFP, TQFP, and TQFP packages. See Table 3.

General

Description

Figure 4. MAX 7000B Parallel Expanders



Unused product terms in a macrocell can be allocated to a neighboring macrocell.

Programmable Interconnect Array

Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000B dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a two-input AND gate, which selects a PIA signal to drive into the LAB.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000B Device

The time required to program a single MAX 7000B device in-system can be calculated from the following formula:

^t PROG	= t _{PPULSE} +	^{Cycle} ртск f _{TCK}
where:	t _{PROG} t _{PPULSE}	Programming timeSum of the fixed times to erase, program, and verify the EEPROM cells
	Cycle _{PTCK} f _{TCK}	Number of TCK cycles to program a deviceTCK frequency

The ISP times for a stand-alone verification of a single MAX 7000B device can be calculated from the following formula:

$t_{VER} = t_{VPULSE} + \frac{C_2}{2}$	^{JCle} VTCK ^f TCK
where: t_{VER} t_{VPULSE} $Cycle_{VTCK}$	= Verify time= Sum of the fixed times to verify the EEPROM cells= Number of TCK cycles to verify a device

Programming with External Hardware	MAX 7000B devices can be programmed on Windows-based PCs with an Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs continuity checking to ensure adequate electrical contact between the adapter and the device.
	For more information, see the <i>Altera Programming Hardware Data Sheet</i> .
	The Altera software can use text- or waveform-format test vectors created with the Altera Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional device behavior with the results of simulation.
	Data I/O, BP Microsystems, and other programming hardware manufacturers provide programming support for Altera devices. For more information, see <i>Programming Hardware Manufacturers</i> .
IEEE Std. 1149.1 (JTAG) Boundary-Scan Support	MAX 7000B devices include the JTAG boundary-scan test circuitry defined by IEEE Std. 1149.1. Table 6 describes the JTAG instructions supported by MAX 7000B devices. The pin-out tables starting on page 59 of this data sheet show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 6. MAX 7000B	Table 6. MAX 7000B JTAG Instructions			
JTAG Instruction	Description			
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.			
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.			
BYPASS	Places the 1-bit bypass register between the TDI and TDO pins, which allows the boundary-scan test data to pass synchronously through a selected device to adjacent devices during normal operation.			
CLAMP	Allows the values in the boundary-scan register to determine pin states while placing the 1-bit bypass register between the TDI and TDO pins.			
IDCODE	Selects the IDCODE register and places it between the TDI and TDO pins, allowing the IDCODE to be serially shifted out of TDO.			
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE value to be shifted out of TDO.			
ISP Instructions	These instructions are used when programming MAX 7000B devices via the JTAG ports with the MasterBlaster or ByteBlasterMV download cable, or using a Jam File (.jam), Jam Byte-Code File (.jbc), or Serial Vector Format File (.svf) via an embedded processor or test equipment.			

The instruction register length of MAX 7000B devices is ten bits. The MAX 7000B USERCODE register length is 32 bits. Tables 7 and 8 show the boundary-scan register length and device IDCODE information for MAX 7000B devices.

Table 7. MAX 7000B Boundary-Scan Register Length			
Device Boundary-Scan Register Lengt			
EPM7032B	96		
EPM7064B	192		
EPM7128B	288		
EPM7256B	480		
EPM7512B	624		

Table 8. 32-Bit MAX 7000B Device IDCODE Note (1)					
Device	IDCODE (32 Bits)				
	Version (4 Bits)	Part Number (16 Bits)Manufacturer's Identity (11 Bits)1 (1 B (2)			
EPM7032B	0010	0111 0000 0011 0010	00001101110	1	
EPM7064B	0010	0111 0000 0110 0100	00001101110	1	
EPM7128B	0010	0111 0001 0010 1000	00001101110	1	
EPM7256B	0010	0111 0010 0101 0110	00001101110	1	
EPM7512B	0010	0111 0101 0001 0010	00001101110	1	

Notes:

(1) The most significant bit (MSB) is on the left.

(2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

See *Application Note* 39 (IEEE 1149.1 (JTAG) *Boundary-Scan Testing in Altera Devices*) for more information on JTAG boundary-scan testing.

Figure 8 shows the timing information for the JTAG signals.

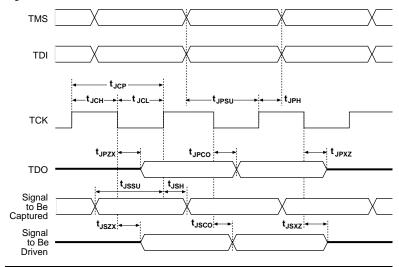


Figure 8. MAX 7000B JTAG Waveforms

Table 9 shows the JTAG timing parameters and values for MAX 7000B devices.

Table 9. Note (1)	JTAG Timing Parameters & Values for MAX 70	00B Dev	ices	
Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns

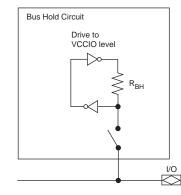
Note:

(1) Timing parameters in this table apply to all V_{CCIO} levels.

Two inverters implement the bus-hold circuitry in a loop that weakly drives back to the I/O pin in user mode.

Figure 10 shows a block diagram of the bus-hold circuit.

Figure 10. Bus-Hold Circuit



PCI Compatibility

MAX 7000B devices are compatible with PCI applications as well as all 3.3-V electrical specifications in the *PCI Local Bus Specification Revision 2.2* except for the clamp diode. While having multiple clamp diodes on a signal trace may be redundant, designers can add an external clamp diode to meet the specification. Table 13 shows the MAX 7000B device speed grades that meet the PCI timing specifications.

Table 13. MAX 7000B Device Speed Grades that Meet PCI Timing Specifications			
Device	Specification		
	33-MHz PCI	66-MHz PCI	
EPM7032B	All speed grades	-3	
EPM7064B	All speed grades	-3	
EPM7128B	All speed grades	-4	
EPM7256B	All speed grades	-5 (1)	
EPM7512B	All speed grades	-5 (1)	

Note:

(1) The EPM7256B and EPM7512B devices in a -5 speed grade meet all PCI timing specifications for 66-MHz operation except the Input Setup Time to CLK—Bused Signal parameter. However, these devices are within 1 ns of that parameter. EPM7256B and EPM7512B devices meet all other 66-MHz PCI timing specifications.

Power Sequencing & Hot-Socketing	Because MAX 7000B devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The $\rm V_{\rm CCIO}$ and $\rm V_{\rm CCINT}$ power planes can be powered in any order.
	Signals can be driven into MAX 7000B devices before and during power- up (and power-down) without damaging the device. Additionally, MAX 7000B devices do not drive out during power-up. Once operating conditions are reached, MAX 7000B devices operate as specified by the user.
	MAX 7000B device I/O pins will not source or sink more than 300 μA of DC current during power-up. All pins can be driven up to 4.1 V during hot-socketing.
Design Security	All MAX 7000B devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security, because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.
Generic Testing	MAX 7000B devices are fully functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 11. Test patterns can be used and then erased during early stages of the production flow.

Table 15. MAX 7000B Device Recommended Operating Conditions Device Recommended Operating Conditions							
Symbol	Parameter	Conditions	Min	Max	Unit		
V _{CCINT}	Supply voltage for internal logic and input buffers	(10)	2.375	2.625	V		
V _{CCIO}	Supply voltage for output drivers, 3.3-V operation		3.0	3.6	V		
	Supply voltage for output drivers, 2.5-V operation		2.375	2.625	V		
	Supply voltage for output drivers, 1.8-V operation		1.71	1.89	V		
V _{CCISP}	Supply voltage during in-system programming		2.375	2.625	V		
VI	Input voltage	(3)	-0.5	3.9	V		
Vo	Output voltage		0	V _{CCIO}	V		
T _A	Ambient temperature	For commercial use	0	70	°C		
		For industrial use (11)	-40	85	°C		
TJ	Junction temperature	For commercial use	0	90	°C		
		For industrial use (11)	-40	105	°C		
t _R	Input rise time			40	ns		
t _F	Input fall time			40	ns		

Figure 12 shows the typical output drive characteristics of MAX 7000B devices.

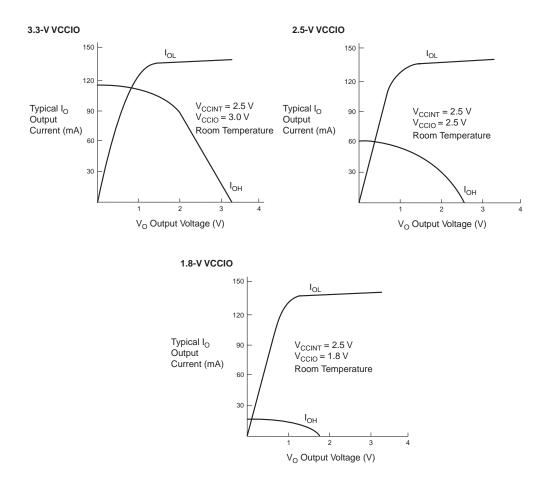


Figure 12. Output Drive Characteristics of MAX 7000B Devices

Symbol	Parameter	Conditions	Speed Grade						
			-3.5		-5.0		-7.5		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		3.5		5.0		7.5	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		3.5		5.0		7.5	ns
t _{SU}	Global clock setup time	(2)	2.1		3.0		4.5		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		1.0		1.0		1.5		ns
t _{FH}	Global clock hold time of fast input		1.0		1.0		1.0		ns
t _{FZHSU}	Global clock setup time of fast input with zero hold time		2.0		2.5		3.0		ns
t _{FZHH}	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	2.4	1.0	3.4	1.0	5.0	ns
t _{CH}	Global clock high time		1.5		2.0		3.0		ns
t _{CL}	Global clock low time		1.5		2.0		3.0		ns
t _{ASU}	Array clock setup time	(2)	0.9		1.3		1.9		ns
t _{AH}	Array clock hold time	(2)	0.2		0.3		0.6		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	3.6	1.0	5.1	1.0	7.6	ns
t _{ACH}	Array clock high time		1.5		2.0		3.0		ns
t _{ACL}	Array clock low time		1.5		2.0		3.0		ns
t _{CPPW}	Minimum pulse width for clear and preset		1.5		2.0		3.0		ns
t _{CNT}	Minimum global clock period	(2)		3.3		4.7		7.0	ns
f _{CNT}	Maximum internal global clock frequency	(2), (3)	303.0		212.8		142.9		MHz
t _{acnt}	Minimum array clock period	(2)		3.3		4.7		7.0	ns
facnt	Maximum internal array clock frequency	(2), (3)	303.0		212.8		142.9		MHz

Tables 18 through 32 show MAX 7000B device timing parameters.

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.3		0.6		0.8	ns
t _{IO}	I/O input pad and buffer delay			0.3		0.6		0.8	ns
t _{FIN}	Fast input delay			1.3		2.9		3.7	ns
t _{FIND}	Programmable delay adder for fast input			1.0		1.5		1.5	ns
t _{SEXP}	Shared expander delay			1.5		2.8		3.8	ns
t _{PEXP}	Parallel expander delay			0.4		0.8		1.0	ns
t _{LAD}	Logic array delay			1.6		2.9		3.8	ns
t _{LAC}	Logic control array delay			1.4		2.6		3.4	ns
t _{IOE}	Internal output enable delay			0.1		0.3		0.4	ns
t _{OD1}	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		0.9		1.7		2.2	ns
t _{OD3}	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5 V \text{ or } 3.3 V$	C1 = 35 pF		5.9		6.7		7.2	ns
t _{ZX1}	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF		1.8		3.3		4.4	ns
t _{ZX3}	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5 V \text{ or } 3.3 V$	C1 = 35 pF		6.8		8.3		9.4	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		1.8		3.3		4.4	ns
t _{SU}	Register setup time		1.0		1.9		2.6		ns
t _H	Register hold time		0.4		0.8		1.1		ns
t _{FSU}	Register setup time of fast input		0.8		0.9		0.9		ns
t _{FH}	Register hold time of fast input		1.2		1.6		1.6		ns
t _{RD}	Register delay			0.5		1.1		1.4	ns
t _{COMB}	Combinatorial delay			0.2		0.3		0.4	ns
t _{IC}	Array clock delay			1.4		2.8		3.6	ns
t _{EN}	Register enable time			1.4		2.6		3.4	ns
t _{GLOB}	Global control delay			1.1		2.3		3.1	ns
t _{PRE}	Register preset time		1	1.0		1.9		2.6	ns
t _{CLR}	Register clear time			1.0		1.9		2.6	ns
t _{PIA}	PIA delay	(2)	1	1.0		2.0		2.8	ns
t _{LPA}	Low-power adder	(4)		1.5		2.8		3.8	ns

I/O Standard	Parameter	Speed Grade						Unit	
		-5		-7		-10		-	
		Min	Max	Min Max		Min	Max	x	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns	
	Input to global clock and clear		0.0		0.0		0.0	ns	
	Input to fast input register		0.0		0.0		0.0	ns	
	All outputs		0.0		0.0		0.0	ns	
2.5 V TTL/CMOS	Input to PIA		0.4		0.6		0.8	ns	
	Input to global clock and clear		0.3		0.5		0.6	ns	
	Input to fast input register		0.2		0.3		0.4	ns	
	All outputs		0.2		0.3		0.4	ns	
1.8 V TTL/CMOS	Input to PIA		0.6		0.9		1.2	ns	
	Input to global clock and clear		0.6		0.9		1.2	ns	
	Input to fast input register		0.5		0.8		1.0	ns	
	All outputs		1.3		2.0		2.6	ns	
SSTL-2 Class I	Input to PIA		1.5		2.3		3.0	ns	
	Input to global clock and clear		1.3		2.0		2.6	ns	
	Input to fast input register		1.1		1.7		2.2	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-2 Class II	Input to PIA		1.5		2.3		3.0	ns	
	Input to global clock and clear		1.3		2.0		2.6	ns	
	Input to fast input register		1.1		1.7		2.2	ns	
	All outputs		-0.1		-0.2		-0.2	ns	
SSTL-3 Class I	Input to PIA		1.4		2.1		2.8	ns	
	Input to global clock and clear		1.1		1.7		2.2	ns	
	Input to fast input register		1.0		1.5		2.0	ns	
	All outputs		0.0		0.0		0.0	ns	
SSTL-3 Class II	Input to PIA		1.4		2.1		2.8	ns	
	Input to global clock and clear		1.1		1.7		2.2	ns	
	Input to fast input register		1.0		1.5		2.0	ns	
	All outputs		0.0		0.0		0.0	ns	
GTL+	Input to PIA		1.8		2.7		3.6	ns	
	Input to global clock and clear		1.8		2.7		3.6	ns	
	Input to fast input register		1.7		2.6		3.4	ns	
	All outputs		0.0		0.0		0.0	ns	

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		-
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.3		0.3		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.3		0.3		0.5	ns
t _{FIN}	Fast input delay			2.2		3.2		4.0	ns
t _{FIND}	Programmable delay adder for fast input			1.5		1.5		1.5	ns
t _{SEXP}	Shared expander delay			1.5		2.1		2.7	ns
t _{PEXP}	Parallel expander delay			0.4		0.5		0.7	ns
t _{LAD}	Logic array delay			1.7		2.3		3.0	ns
t _{LAC}	Logic control array delay			1.5		2.0		2.6	ns
t _{IOE}	Internal output enable delay			0.1		0.2		0.2	ns
t _{OD1}	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		0.9		1.2		1.6	ns
t _{OD3}	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5$ V or 3.3 V	C1 = 35 pF		5.9		6.2		6.6	ns
t _{ZX1}	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF		2.8		3.8		5.0	ns
t _{ZX3}	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5 V \text{ or } 3.3 V$	C1 = 35 pF		7.8		8.8		10.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		2.8		3.8		5.0	ns
t _{SU}	Register setup time		1.5		2.0		2.6		ns
t _H	Register hold time		0.4		0.5		0.7		ns
t _{FSU}	Register setup time of fast input		0.8		1.1		1.1		ns
t _{FH}	Register hold time of fast input		1.2		1.4		1.4		ns
t _{RD}	Register delay			0.5		0.7		1.0	ns
t _{COMB}	Combinatorial delay			0.2		0.3		0.4	ns
t _{IC}	Array clock delay			1.8		2.4		3.1	ns
t _{EN}	Register enable time			1.5		2.0		2.6	ns
t _{GLOB}	Global control delay			2.0		2.8		3.6	ns
t _{PRE}	Register preset time			1.0		1.4		1.9	ns
t _{CLR}	Register clear time			1.0		1.4		1.9	ns
t _{PIA}	PIA delay	(2)		2.4		3.4		4.5	ns
t _{LPA}	Low-power adder	(4)	1	2.0	1	2.7		3.6	ns

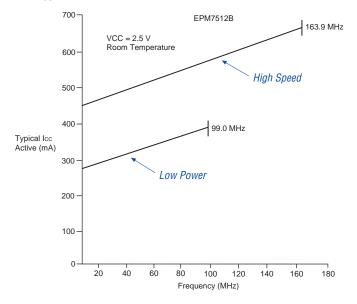


Figure 19. I_{CC} vs. Frequency for EPM7512B Devices



Package outline not drawn to scale.

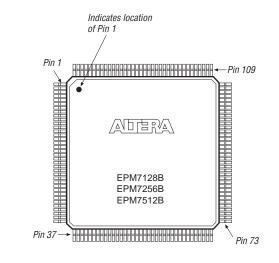
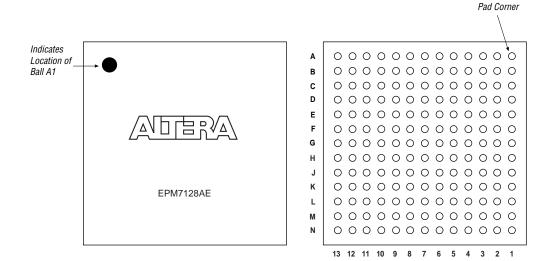


Figure 26. 169-Pin Ultra FineLine BGA Pin-Out Diagram

Package outline not drawn to scale.



A1 Ball



Package outline not drawn to scale.

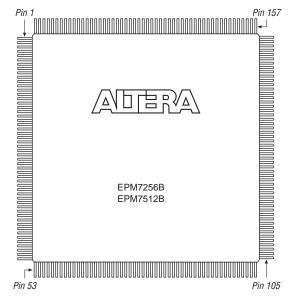


Figure 28. 256-Pin BGA Package Pin-Out Diagram

Package outline not drawn to scale.

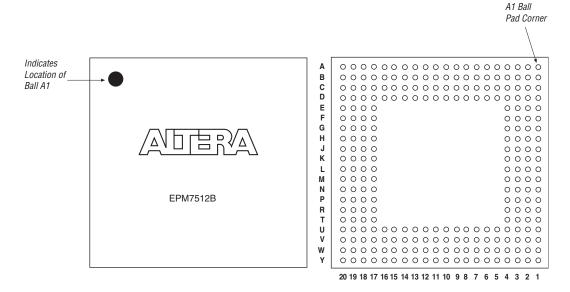


Figure 29. 256-Pin FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.



Revision History

The information contained in the *MAX* 7000B Programmable Logic Device Family Data Sheet version 3.5 supersedes information published in previous versions.

Version 3.5

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.5:

■ Updated Figure 28.

Version 3.4

The following changes were made to the *MAX* 7000B Programmable Logic Device Family Data Sheet version 3.4:

Updated text in the "Power Sequencing & Hot-Socketing" section.

Version 3.3

The following changes were made to the *MAX 7000B Programmable Logic Device Family Data Sheet* version 3.3:

- Updated Table 3.
- Added Tables 4 through 6.

Version 3.2

The following changes were made to the *MAX* 7000B Programmable Logic Device Family Data Sheet version 3.2:

 Updated Note (10) and added ambient temperature (T_A) information to Table 15.

Version 3.1

The following changes were made to the *MAX* 7000B Programmable Logic Device Family Data Sheet version 3.1:

- Updated V_{IH} and V_{IL} specifications in Table 16.
- Updated leakage current conditions in Table 16.

Version 3.0

The following changes were made to the *MAX* 7000B Programmable Logic Device Family Data Sheet version 3.0:

- Updated timing numbers in Table 1.
- Updated Table 16.
- Updated timing in Tables 18, 19, 21, 22, 24, 25, 27, 28, 30, and 31.



101 Innovation Drive San Jose, CA 95134 (408) 544-7000 http://www.altera.com Applications Hotline: (800) 800-EPLD Customer Marketing: (408) 544-7104 Literature Services: lit_req@altera.com

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